

# PLUS

	L #	Hits	Search Text	DBs	Time Stamp	Type
1	L7	50	("6292830" "5708776" "5295522" "6171367" "5674123" "5848933" "6120371" "4598668" "5561317" "5731131" "5265102" "5206938" "5461474" "5675467" "6141768" "4398208" "4415851" "6576563" "5369377" "5567388" "6073200" "6114880" "5214849" "5317802" "5781447" "5965860" "6328793" "5329471" "5821614" "4303341" "4412240" "4453834" "4479298" "4524280" "4755661" "4763124" "4805110" "4855778" "4874721" "4910508" "5248358" "5367150" "5473166" "5475695" "5535331" "5576969" "5623395" "5694139" "5754559" "5790381").pn.	USPAT; USOCR	2005/03/20 16:46	BRS

10/821156

Most Frequently Occurring Classifications of Patents Returned  
From A Search of 10821156 on November 26, 2004

## Original Classifications

3 454/187  
2 250/548  
2 361/735

## Cross-Reference Classifications

3 174/52.4  
3 235/375  
3 414/940  
2 174/138G  
2 235/376  
2 257/685  
2 257/686  
2 257/713  
2 257/717  
2 257/730  
2 257/797  
2 257/E23.173  
2 361/730  
2 361/732  
2 361/820  
2 714/28  
2 714/30  
2 716/19

## Combined Classifications

3 174/52.4  
3 235/375  
3 414/940  
3 454/187  
3 716/19  
2 174/138G  
2 235/376  
2 235/380  
2 235/382  
2 235/492  
2 250/548  
2 257/685  
2 257/686  
2 257/713  
2 257/717  
2 257/730  
2 257/797  
2 257/E23.173  
2 361/730  
2 361/732  
2 361/735  
2 361/820  
2 700/121  
2 714/28  
2 714/30

	L #	Hits	Search Text	DBs	Time Stamp	Type
1	L1	10092	gas ADJ purg\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 15:57	BRS
2	L2	40218	"700".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 15:57	BRS
3	L3	164129	"438".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 15:57	BRS
4	L4	760	L1 AND (L2 OR L3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 16:02	BRS
5	L5	51	L4 AND ("operating system" OR MES OR MCS OR "manufacturing execution system" OR "material control system")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 16:23	BRS
6	L6	11	L4 AND L1 WITH (automat\$ OR computeriz\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 16:45	BRS

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	L #	Hits	Search Text	DBs	Time Stamp	Type
1	L9	752	(station OR workstation OR device OR machine OR tool OR chamber) SAME ((gas OR nitrogen) ADJ purg\$3) SAME (sputter\$3 OR "cvd" OR deposit\$3 OR "rtp" OR "rapid thermal")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 18:19	BRS
2	L10	291	L9 AND (L2 OR L3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 18:19	BRS
3	L11	52	L9 SAME (controller OR "plc" OR computer OR processor OR "pc" OR "nc" OR "cpu")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 17:40	BRS
4	L12	11	L10 AND L11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 17:45	BRS
5	L13	41	L11 NOT L12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 17:45	BRS
6	L14	179	(station OR workstation OR device OR machine OR tool OR chamber) SAME (((gas OR nitrogen) ADJ purg\$3) OR sputter\$3 OR "cvd" OR deposit\$3 OR "rtp" OR "rapid thermal") SAME ("operating system" OR "MES" OR "MCS" OR "manufacturing execution system" OR "material control system") SAME (controller OR "plc" OR computer OR processor OR "pc" OR "nc" OR "cpu")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 18:10	BRS
7	L15	39	L14 SAME (queu\$3 OR dispatch\$3 OR schedul\$3 OR buffer\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 18:18	BRS
8	L16	863	"front opening unified pod" OR "FOUP"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 18:18	BRS
9	L17	137	L16 AND (L2 OR L3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 18:19	BRS
10	L18	1	L16 SAME ((gas OR nitrogen) ADJ purg\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/20 18:19	BRS

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File View Edit Tools Window Help										
ACTIVE										
1	Document ID	Source	Issue Date	Title	Current	Inventor	3	4	Image Doc	D P
1	US 5953591 A	USPAT	19990914	Process for laser detection of gas and contaminants in a wafer transport gas tunnel	438/115	Ishihara, Yoshio et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 5953591
2	US 20040137755 A1	US-PG PUB	20040715	System and method for hydrogen-rich selective oxidation	438/770	Herring, Robert B. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20040137755
3	US 6821891 B2	USPAT	20041123	Atomic layer deposition of copper using a reducing gas and non-fluorinated copper precursors	438/687	Chen, Ling et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6821891
4	US 5428555 A	USPAT	19950627	Facility and gas management system	700/275	Starkey, Sean C. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 5428555
5	US 20050009325 A1	US-PG PUB	20050113	Atomic layer deposition of barrier materials	438/637	Chung, Hua et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20050009325
6	US 20030019839 A1	US-PG PUB	20030130	Maintenance method and system for plasma processing apparatus etching and apparatus	216/60	Yamamoto, Hideyuki et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20030019839
7	US 20020151188 A1	US-PG PUB	20021017	Apparatus and method for detecting an end point of chamber cleaning in semiconductor equipment	438/758	Cui, Zhenjiang et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20020151188
8	US 6120371 A	USPAT	20000919	Docking and environmental purging system for integrated circuit wafer transport assemblies	454/187	Roberson, Jr., Glenn A. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6120371
9	US 5848933 A	USPAT	19981215	Docking and environmental purging system for integrated circuit wafer transport assemblies	454/187	Roberson, Jr., Glenn A. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 5848933
10	US 5674123 A	USPAT	19971007	Docking and environmental purging system for integrated circuit wafer transport assemblies	454/187	Roberson, Jr., Glenn A. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 5674123
11	US 5461474 A	USPAT	19951024	Inspection apparatus for detecting foreign matter on a surface to be inspected, and an exposure apparatus and a device manufacturing method using the same	356/237-4	Yoshii, Minoru et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 5461474
12	US 5295522 A	USPAT	19940322	Gas purge system for isolation enclosure for contamination sensitive items	141/99	DeAngelis, Robert L. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 5295522
13	US 6287114 B1	USPAT	20011002	Semiconductor device and process and apparatus of fabricating the same	438/305	Iwata, Hiroshi et al.	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6287114
14	US 6444137 B1	USPAT	20020803	Method for processing substrates using gaseous silicon scavenger	216/79	Collins, Kenneth S. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6444137
15	US 6224676 B1	USPAT	20010501	Gas supply apparatus and film forming apparatus	118/707	Nakajima, Katsunori et al.	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6224676
16	US 5880500 A	USPAT	19990309	Semiconductor device and process and apparatus of fabricating the same	257/336	Iwata, Hiroshi et al.	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5880500
17	US 5871805 A	USPAT	19990216	Computer controlled vapor deposition processes	427/8	Lemelson, Jerome	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 5871805
18	US 5728222 A	USPAT	19980317	Apparatus for chemical vapor deposition of aluminum oxide	118/715	Barbee, Steven George et al.	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5728222
19	US 5614247 A	USPAT	19970325	Apparatus for chemical vapor deposition of aluminum oxide	427/8	Barbee, Steven G. et al.	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5614247
20	US 5241851 A	USPAT	19930907	Method of performing an instantaneous moisture concentration measurement and for determining the rundown characteristics of an environment	73/29.01	Tapp, Frederick et al.	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5241851
21	US 20040083961 A1	US-PG PUB	20040508	Gas delivery system for pulsed-type deposition processes used in the manufacturing of micro-devices	118/715	Bascen, Cem	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20040083961
22	US 20040003777 A1	US-PG PUB	20040109	Apparatus and method for depositing materials onto microelectronic workpieces	118/715	Carpenter, Craig M. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20040003777
23	US 6678570 B1	USPAT	20040113	Method and apparatus for determining output characteristics using tool state data	700/109	Pasady, Alexander J. et al.	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6678570
24	US 6583509 B2	USPAT	20030624	Semiconductor processing techniques	257/773	Nulman, Jaim	<input type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6583509
25	US 6456894 B1	USPAT	20020824	Semiconductor processing techniques	700/121	Nulman, Jaim	<input type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6456894
26	US 6408220 B1	USPAT	20020618	Semiconductor processing techniques	700/121	Nulman, Jaim	<input type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6408220
27	US 6303395 B1	USPAT	20011016	Semiconductor processing techniques	438/14	Nulman, Jaim	<input type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6303395
28	US 20020184242 A1	US-PG PUB	20021107	Control system for transfer and buffering	700/214	Wehrung, Brian et al.	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20020184242
29	US 20020023329 A1	US-PG PUB	20020228	Semiconductor processing techniques	29/25.01	Nulman, Jaim	<input type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 20020023329
30	US 6597964 B1	USPAT	20030722	Thermocoupled lift pin system for etching chamber	700/121	Huang, Yu-Chih et al.	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6597964

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